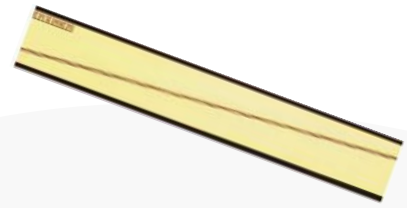


High Power SOA Chip



Part Number: CHP-315L

High Power SOA Chip
Single-Mode SOA
Wavelength at 1595nm, L-Band



Features

- High Output Power
- High Dynamic Range
- High Efficiency
- Standard SOA Bare Die
- Cost Effective

Application

- OTDR
- LiDAR
- Free Space Communications
- Network Test Equipment



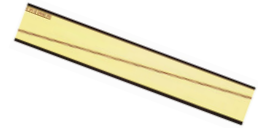
SemiNex delivers the highest available power at infrared wavelengths between 12xx and 19xx nm. When necessary, we will further optimize the design of our InP & GaSb laser chips to meet our customers' specific optical and electrical performance needs. Diodes, bars and packages are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or to discuss your specific requirements.

High Power SOA Chip



Specification

CHP-315L



Optical	Symbol	Typ.	Units
Center Wavelength	λ_c	1595	nm
Output Power @ 1A*	P_{out}	0.39	Watts ($\pm 10\%$)
Aperture Width	AW	4	μm
Gain @ Pin = 10 μ W	G	33	dB
Beam Exit Angle	θ_{EXT}	19.5	Degree
Noise Figure	NF	7	dB
Polarization Extinction Ratio	PER	18	dB
Fast Axis Div.	$\theta_{\perp}$	30	Deg FWHM
Slow Axis Div.	$\theta_{\parallel}$	20	Deg FWHM
Front Facet Reflectivity		<0.1%	
Rear Face Reflectivity		<0.1%	
Waveguide		Tilted Straight	
Electrical	Symbol		Units
Operating Current	I_{op}	1	A
Operating Voltage	V_{op}	2	V
Mechanical		Range	Units
Chip Length		2500	μm
Chip Width		500	μm
Operating Temp.**		-20 to 75	$^{\circ}C$
Storage Temp.		-40 to 85	$^{\circ}C$

*Optical Power for 1595nm COC-315L with SOA drive current @ 1A and estimated Pin @ 21mW

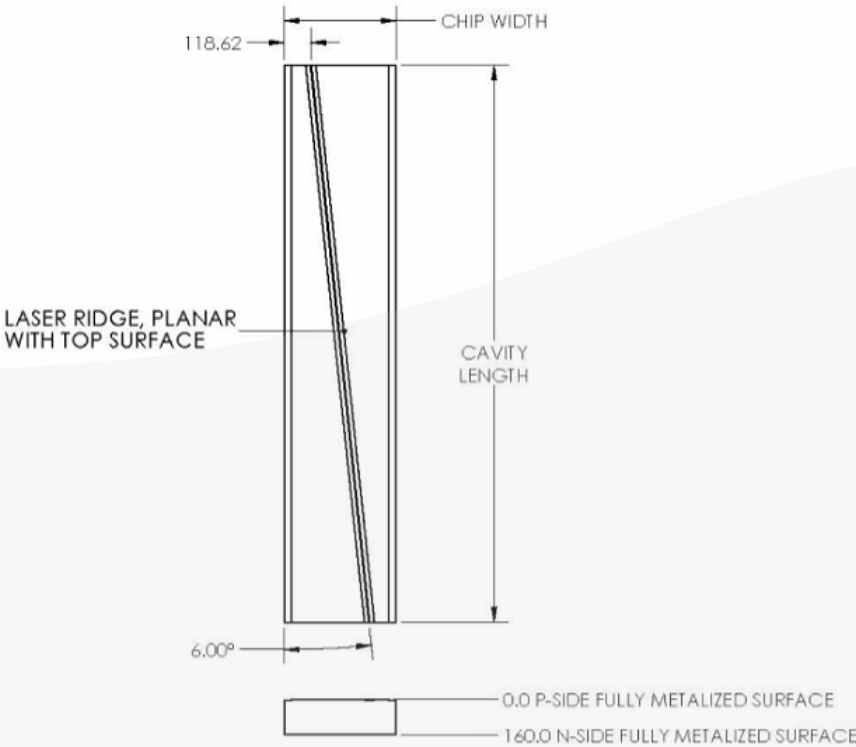
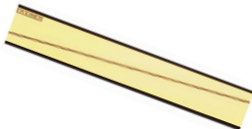
* Optical output power depends on the seed laser power, coupling efficiency, and thermal management.

*Specified values are rated at a constant heat sink temperature of 20 $^{\circ}C$.

**High temperature operation will reduce performance and MTTF.

Unless otherwise indicated all values are nominal.

High Power SOA Chip



CHIP ATTRIBUTES	
WAVELENGTH	1595nm ± 20 nm
APERTURE WIDTH	4 μ m $\pm 1\mu$ m
CHIP WIDTH	0.500mm $\pm 10\mu$ m
THICKNESS	160 μ m $\pm 10\mu$ m
CAVITY LENGTH	2.5mm $\pm 10\mu$ m

P-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	50	± 10
Pt	125	± 25
Au	250	± 50

N-METAL		
MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	30	± 10
Pt	125	± 25
Au	400	± 40

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*Graphs and Data were collected from mounted parts